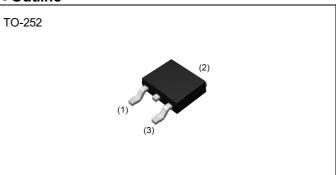
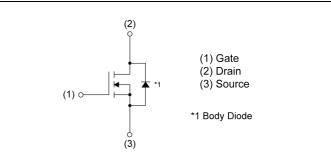


V _{DSS}	600V
R _{DS(on)} (Max.)	830mΩ
Ι _D	±6A
P _D	70W

Outline



Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL1
Marking	R6006K
Basic ordering unit (pcs)	2500

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain - Source voltage		V _{DSS}	600	V
Continuous drain current $(T_c = 2)$	5°C)	۱ _D *1	±6	А
Pulsed drain current	I_{DP}^{*2}	±18	А	
Octo Octores un literas	static		±20	V
Gate - Source voltage	AC(f>1Hz)	V _{GSS}	±30	V
Avalanche current, single pulse		I_{AS}^{*3}	1.1	А
Avalanche energy, single pulse		E _{AS} *3	65	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P _D	70	W	
Junction temperature	Τ _j	150	°C	
Operating junction and storage te	emperature range	T _{stg}	-55 to +150	°C

Features

1) Low on-resistance

3) Parallel use is easy

2) Ultra fast switching speed

4) Pb-free plating ; RoHS compliant

Application

Switching

•Thermal resistance

Deremeter	Cymab al	Values			1 1
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*4}	-	-	1.8	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics (T_a = 25°C)

Parameter	Sumbol	Symbol Conditions -		Values			
Parameter	Зупрог	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	600	-	-	V	
		V _{DS} = 600V, V _{GS} = 0V					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μA	
		T _j = 125°C	-	-	1000		
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 1mA	3.5	-	5.5	V	
		V _{GS} = 10V, I _D = 3.0A					
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$T_j = 25^{\circ}C$	-	720	830	mΩ	
		$T_j = 125^{\circ}C$	-	1600	-		
Gate resistance	R_G	f = 1MHz, open drain	-	3.4	-	Ω	



•Electrical characteristics (T_a = 25°C)

Deremeter	Symbol		Values			Lincit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Y _{fs} ^{*5} V _E		V _{DS} = 10V, I _D = 3.0A	1.5	3.0	-	S	
Input capacitance	C _{iss}	V _{GS} = 0V	-	350	-		
Output capacitance	C _{oss}	V _{DS} = 25V	-	350	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	20	-		
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 300$ V, V_{GS} = 10V	-	17	-		
Rise time	t _r *5	I _D = 3.0A	-	22	-	20	
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 100\Omega$	-	30	-	ns	
Fall time	t _f *5	R _G = 10Ω	-	30	-		

• Gate charge characteristics (T_a = 25°C)

Deremeter	Symbol Conditions		Values			- Unit	
Parameter			Min.	Тур.	Max.	Unit	
Total gate charge	Qg	V _{DD} ≃ 300V	-	12	-		
Gate - Source charge	Q _{gs} *5	I _D = 6A	-	3.5	-	nC	
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	5.6	-		
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 300$ V, I _D = 6A	-	6.2	-	V	

*1 Limited only by maximum channel temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \doteqdot 100mH, V_{DD}=50V, R_G=25 Ω , STARTING T_j=25°C

*4 T_C=25°C

*5 Pulsed



•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Source current	I _S *1	$T = 25^{\circ}$	-	-	6	А	
Pulsed source current	I_{SP}^{*2}	T _C = 25°C	-	-	18	А	
Source-Drain voltage	V_{SD}^{*5}	V _{GS} = 0V, I _S = 6A	-	-	1.5	V	
Reverse recovery time	t _{rr} *5		-	290	-	ns	
Reverse recovery charge	()	I _S = 6A di/dt = 100A/µs	-	2.2	-	μC	
Peak reverse recovery current	۱ _{.۳} *5		-	15	-	А	





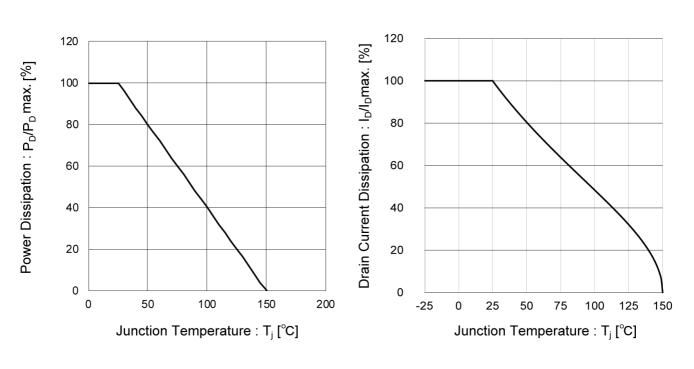


Fig.1 Power Dissipation Derating Curve

Fig.3 Transient Thermal Resistance

vs. Pulse Width

Fig.4 Maximum Safe Operating Area

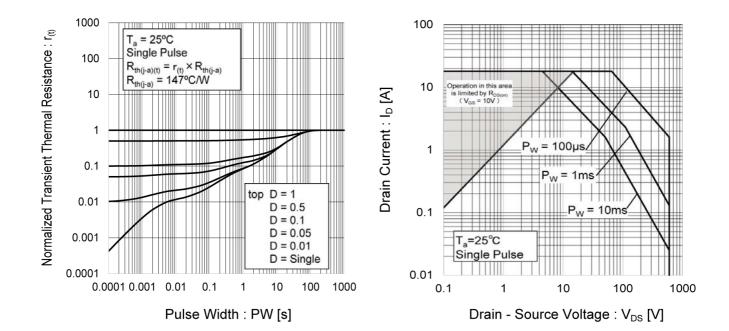


Fig.2 Drain Current Derating Curve





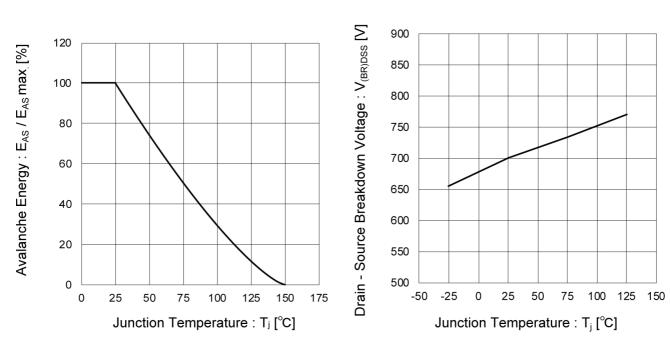


Fig.5 Avalanche Energy DeratingCurve vs. Junction Temperature

Fig.7 Typical Output Characteristics(I)

Drain Current : I_D [A]

6

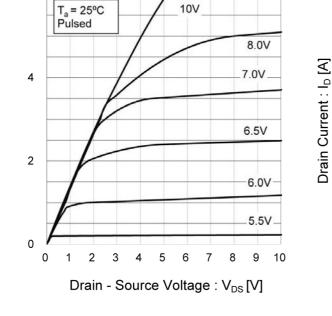
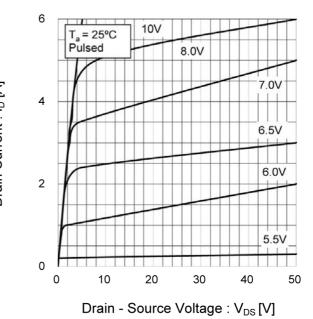


Fig.8 Typical Output Characteristics(II)

Fig.6 Breakdown Voltage

vs. Junction Temperature





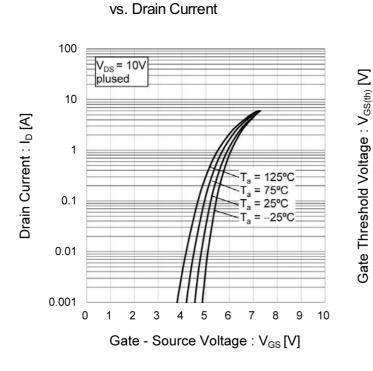


Fig.9 Gate Threshold Voltage

Fig.10 Gate Threshold Voltage vs. Junction Temperature

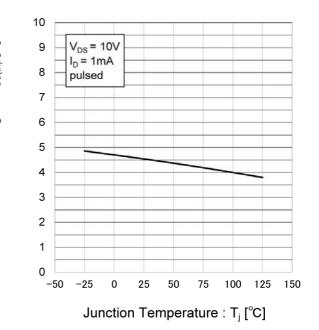
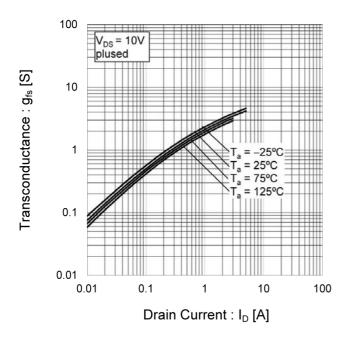


Fig.11 Forward Transfer Admittance vs. Drain Current





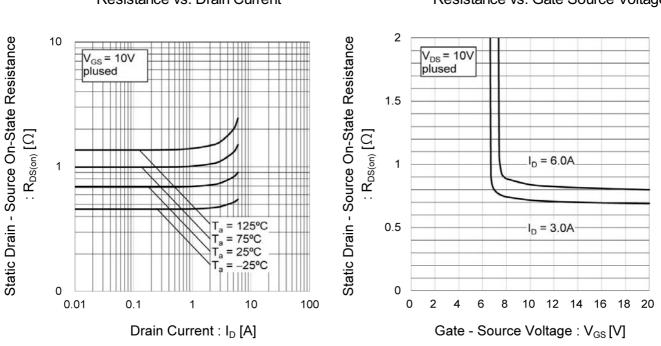


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current Fig.13 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

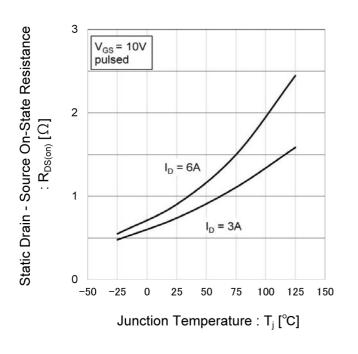
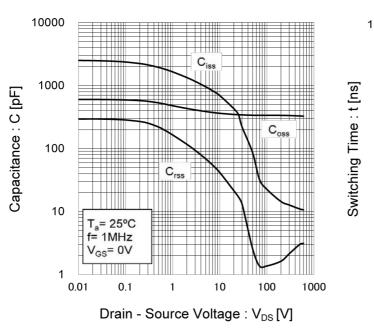


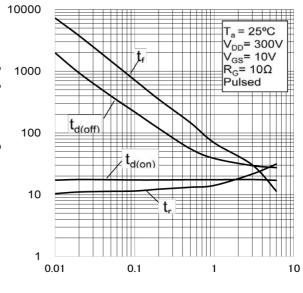


Fig.15 Typical Capacitance



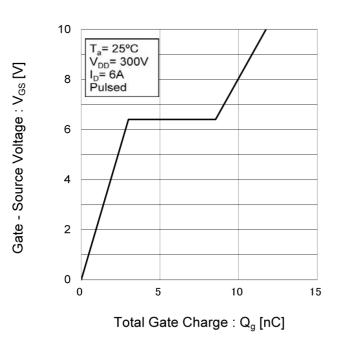
vs. Drain - Source Voltage

Fig.16 Switching Characteristics



Drain Current : I_D [A]

Fig.17 Typical Gate Charge





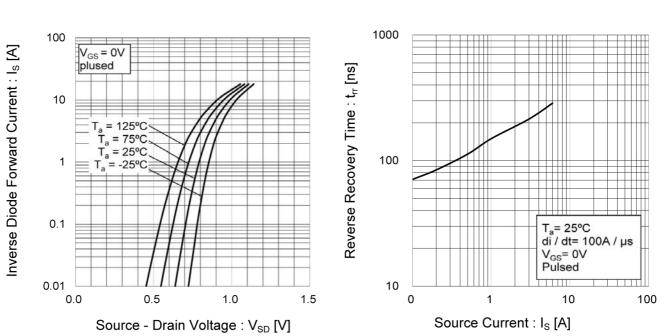


Fig.18 Source Current vs. Source - Drain Voltage Fig.19 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

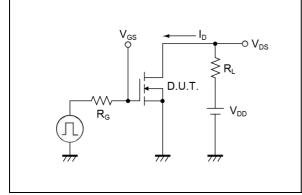


Fig.2-1 Gate Charge Measurement Circuit

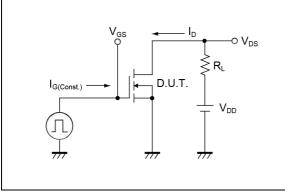


Fig.3-1 Avalanche Measurement Circuit

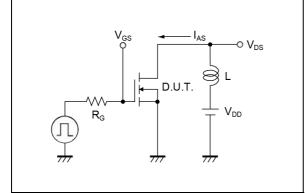


Fig.4-1 Reverse Recovery Time Measurement Circuit

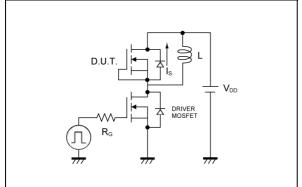


Fig.1-2 Switching Waveforms

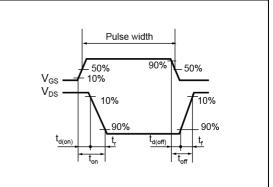


Fig.2-2 Gate Charge Waveform

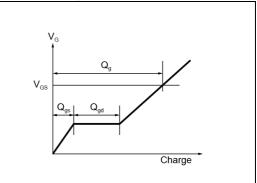


Fig.3-2 Avalanche Waveform

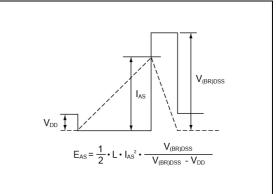
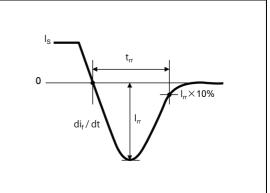
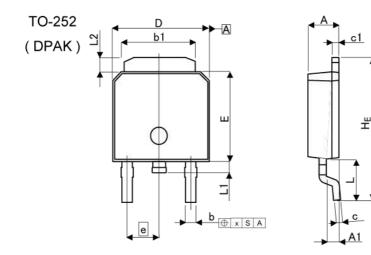


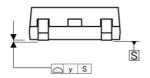
Fig.4-2Reverse Recovery Time Waveform

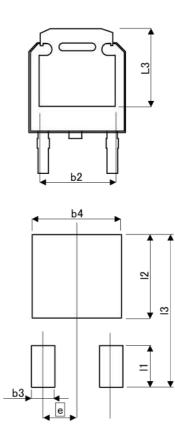




Dimensions







Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INCI	HES
DIM	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	5.	35	0.2	211
с	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	70	0.1	06
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
x	(2) -	0.25	9	0.010
У	(T.)	0.10	-	0.004

DIM	MILIME	ETERS	INCHES		
	MIN	MAX	MIN	MAX	
b3	3 <u>2</u> N	1.15	<u>_</u>	0.045	
b4		5.55	×	0.219	
11	/留//	2.77	¥	0.109	
12		5.50	-	0.217	
13	-	10.40	2	0.409	

Dimension in mm/inches



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1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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